

RHM-US020052

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of

Takaoka et al.	:	Group Art Unit:	2811
	:		
Serial No.: 10/605,585	:	Examiner:	Ori Nadav
	:		
Filed:	October 10, 2003	:	
		:	
For:	Unitary non-layered semiconductor substrate having thin portion formed therein		

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants wish to disclose the following information:

Attached is an Office Actions issued by the Japan Patent Office for a patent application corresponding to the present application. Either the Japanese references cited therein, or the U.S. patents corresponding to the Japanese references cited therein, are listed on the concurrently filed PTO/SB/08a. Applicants request that these references be considered and made of record in this application.

This Information Disclosure Statement is being filed with a certification statement under 37 CFR §1.97, provided in the concurrently filed PTO/SB/08a. Thus, *no fee is believed to be due for this Information Disclosure Statement*. However, the commissioner is authorized to charge any fees associated with this communication or credit any overpayment to Deposit Account 19-2042.

Respectfully submitted,

/Steven Roberts/

Steven Roberts
Reg. No. 39,346

Shinju Global IP
c/o GLOBAL IP COUNSELORS, LLP
1233 Twentieth Street, NW, Suite 700
Washington, DC 20036
(202)-293-0444